

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Katsuhiro KANDA</td> <td>01/27/2012</td> </tr> <tr> <td>Makoto NOGAMI</td> <td>01/30/2012</td> </tr> <tr> <td>Izumi WAKI</td> <td>01/31/2012</td> </tr> </tbody> </table>		Name	Execution Date	Katsuhiro KANDA	01/27/2012	Makoto NOGAMI	01/30/2012	Izumi WAKI	01/31/2012
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<table border="1"> <tr> <td>Name:</td> <td>HITACHI HIGH-TECHNOLOGIES CORPORATION</td> </tr> <tr> <td>Street Address:</td> <td>24-14, Nishi Shimbashi 1-chome, Minato-ku</td> </tr> <tr> <td>City:</td> <td>Tokyo</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> </table>		Name:	HITACHI HIGH-TECHNOLOGIES CORPORATION	Street Address:	24-14, Nishi Shimbashi 1-chome, Minato-ku	City:	Tokyo	State/Country:	JAPAN
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PROPERTY NUMBERS Total: 1									
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CORRESPONDENCE DATA									
<p>Fax Number: (703)684-1157          Phone: 7036841120          Email: jange@mmpiaw.com  <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i></p> <p>Correspondent Name: Mattingly &amp; Malur, PC          Address Line 1: 1800 Diagonal Road          Address Line 2: Suite 370          Address Line 4: Alexandria, VIRGINIA 22314</p>									
ATTORNEY DOCKET NUMBER:	KAS-8199								
NAME OF SUBMITTER:	John R. Mattingly								
Total Attachments: 1 source=8199Assignment#page1.tif									

CH \$40.00 13387229

# ASSIGNMENT

( 譲 渡 証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI HIGH-TECHNOLOGIES CORPORATION, a corporation organized under the laws of Japan, located at 24-14, Nishi Shimbashi 1-chome, Minato-ku, Tokyo, 105-8717 Japan receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI HIGH-TECHNOLOGIES CORPORATION, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

## SPECIMEN PROCESSING SYSTEM

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI HIGH-TECHNOLOGIES CORPORATION, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI HIGH-TECHNOLOGIES CORPORATION,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)  
(発明者フルネームサイン)

Date Signed  
(署名日)

1) <u>Katsuhiko Kanda</u> Katsuhiko KANDA	<u>1 / 27 / 2012</u>
2) <u>makoto nogami</u> Makoto NOGAMI	<u>1 / 30 / 2012</u>
3) <u>Izumi Waki</u> Izumi WAKI	<u>1 / 31 / 2012</u>
4) _____	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____